

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 09275160
PUBLICATION DATE : 21-10-97

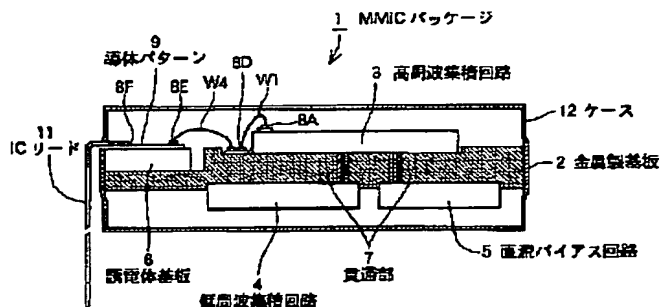
APPLICATION DATE : 03-04-96
APPLICATION NUMBER : 08081764

APPLICANT : HONDA MOTOR CO LTD;

INVENTOR : URABE MASANOBU;

INT.CL. : H01L 23/12 H01L 23/12 H01L 23/14

TITLE : MMIC PACKAGE



ABSTRACT : PROBLEM TO BE SOLVED: To realize high density packaging and prevent mutual interference between a high frequency integrated circuit, a low frequency integrated circuit, and a bias circuit, by arranging the high frequency integrated circuit on one surface of a metal substrate, and arranging the low frequency integrated circuit or the DC bias circuit on the other surface of the metal substrate.

SOLUTION: In an MMIC package 1, a high frequency integrated circuit 3 and a dielectric board 6 are arranged on one surface of a metal substrate 2, and a low frequency integrated circuit 4 and a DC bias circuit 5 are arranged on the other surface of the metal substrate 2. By sealing them with a case 12 composed of mold resin of ceramic or metal, a hybrid integrated circuit is formed. The high frequency integrated circuit 3 is isolated from the low frequency circuit 4 and the DC bias circuit 5 by the metal substrate 2. Mutual interference due to the difference of frequency bands of the high frequency integrated circuit 3, the low frequency integrated circuit 4 and the DC bias circuit 5 is prevented. As a result, many IC chips are mounted in a limited space, and packaging is enabled.

COPYRIGHT: (C)1997,JPO